

	L #	Hits	Search Text	DBs
1	L1	164937	"438"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
2	L2	604	1 and (MEMS or microelectromechanical or microscopic or microsystem) near (structure or device)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
3	L3	105	2 and (hermetic\$4 or pressure) near (seal\$3 or encapsulation)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
4	L4	1	3 and (seal\$3 near (throughhole or hole?))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
5	L6	5	5 and laser	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
6	L5	8	3 and (molten or melt\$3) near material	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
7	L7	5	cheung-kin-p.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
8	L8	626	((MEMS or microelectromechanical or microscopic or microsystem) near (structure or device)) .ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
9	L9	5	8 and ((hermetic\$4 or pressure) near (packaging or seal\$3 or encapsulation)) .ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
10	L10	5627	((MEMS or microelectromechanical or microscopic or microsystem) near (structure or device))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
11	L11	419	10 and (hermetic\$4 or pressure) near (seal\$3 or encapsulation or cap)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
12	L12	181	11 and (throughhole or hole? or passage?)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
13	L13	28	12 and (seal\$3 or molten or melt\$3) near material	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB
14	L14	24	13 and heat\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB

	L #	Hits	Search Text	DBs
15	L155		14 and solidif\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB